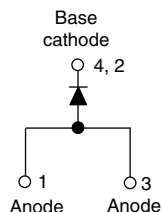


Surface Mountable Input Rectifier Diode, 8 A



D-PAK



FEATURES

- Material categorization:
For definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

DESCRIPTION

The 8EWS..SPbF rectifier High Voltage Series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The **high reverse voltage** range available allows design of input stage primary rectification with **outstanding voltage surge** capability.

Typical applications are in input rectification and these products are designed to be used with Vishay Semiconductors switches and output rectifiers which are available in identical package outlines.

This product has been designed and qualified for industrial level.

PRODUCT SUMMARY

Package	D-PAK (TO-252AA)
$I_{F(AV)}$ at $T_C = 116\text{ °C}$	8 A
V_R	800 V, 1200 V
V_F at I_F	1.1 V
I_{FSM}	200 A
T_J max.	150 °C
Diode variation	Single die

OUTPUT CURRENT IN TYPICAL APPLICATIONS

APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 µm) copper	1.2	1.6	A
Aluminum IMS, $R_{thCA} = 15\text{ °C/W}$	2.5	2.8	
Aluminum IMS with heatsink, $R_{thCA} = 5\text{ °C/W}$	5.5	6.5	

Note

- $T_A = 55\text{ °C}$, $T_J = 125\text{ °C}$, footprint 300 mm²

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform at $T_C = 116\text{ °C}$	8	A
V_{RRM}		800/1200	V
I_{FSM}		200	A
V_F	8 A, $T_J = 25\text{ °C}$	1.10	V
T_J		- 55 to 150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
8EWS08SPbF	800	900	0.5
8EWS12SPbF	1200	1300	

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 105\text{ }^{\circ}\text{C}$, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	170	
		10 ms sine pulse, no voltage reapplied	200	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	130	A^2s
		10 ms sine pulse, no voltage reapplied	145	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1\text{ ms to }10\text{ ms}$, no voltage reapplied	1450	$\text{A}^2\sqrt{\text{s}}$

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop	V_{FM}	8 A, $T_J = 25\text{ }^{\circ}\text{C}$	1.1	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$	20	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$		0.82	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	0.05	mA
		$T_J = 150\text{ }^{\circ}\text{C}$	0.50	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		- 55 to 150	$^{\circ}\text{C}$
Soldering temperature	T_S		240	
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	2.5	$^{\circ}\text{C/W}$
Typical thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Approximate weight			1	g
			0.03	oz.
Marking device		Case style D-PAK (TO-252AA)	8EWS12S	

Note

- ⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^{\circ}\text{C/W}$
For recommended footprint and soldering techniques refer to application note #AN-994

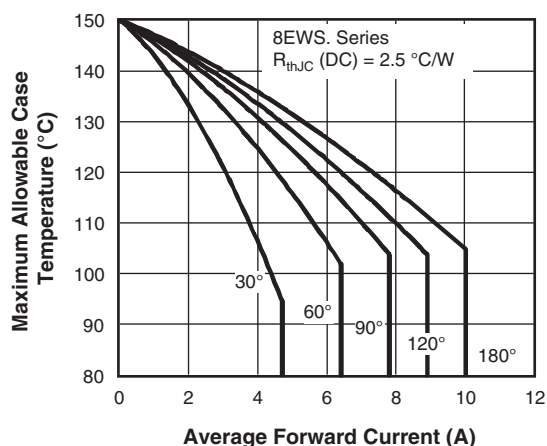


Fig. 1 - Current Rating Characteristics

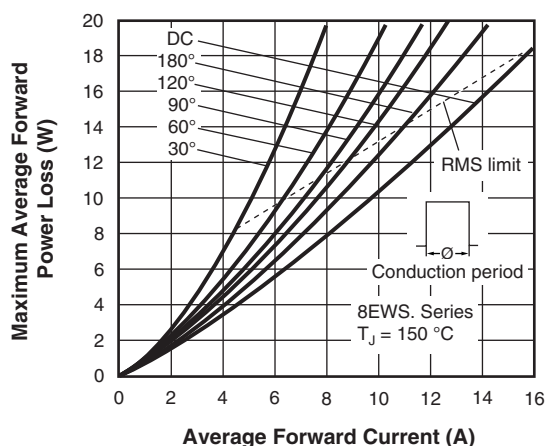


Fig. 4 - Forward Power Loss Characteristics

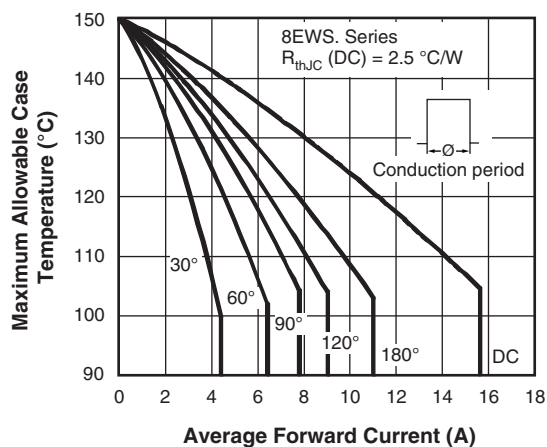


Fig. 2 - Current Rating Characteristics

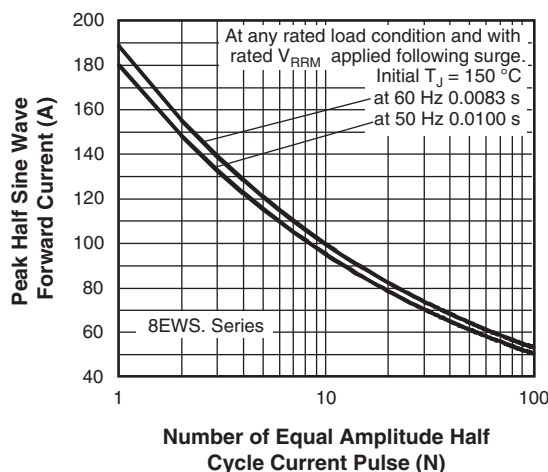


Fig. 5 - Maximum Non-Repetitive Surge Current

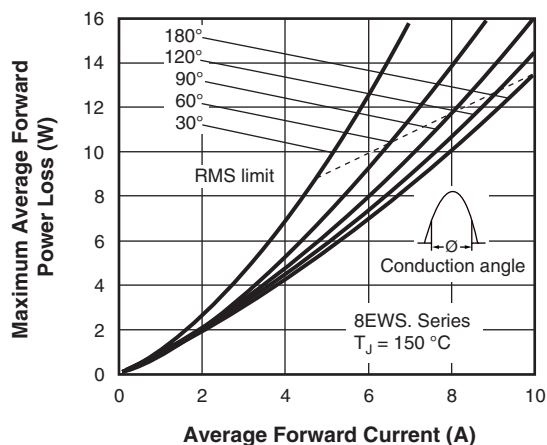


Fig. 3 - Forward Power Loss Characteristics

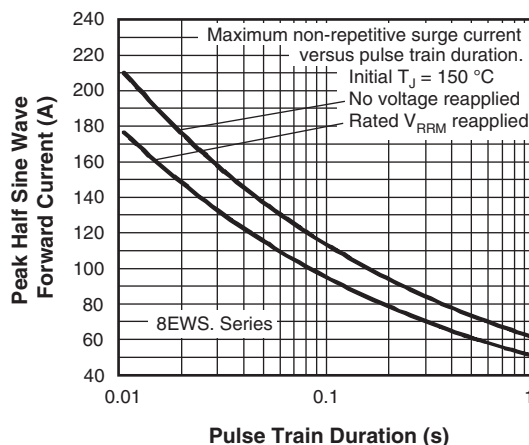


Fig. 6 - Maximum Non-Repetitive Surge Current

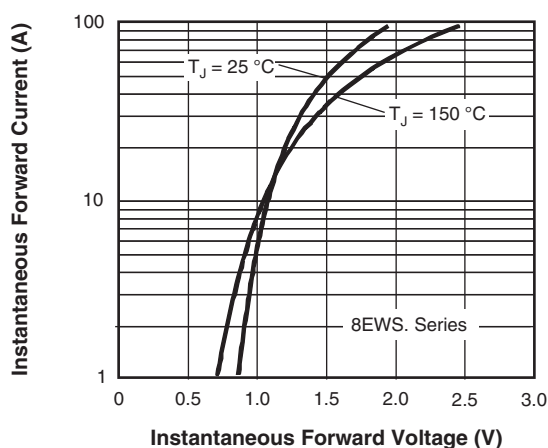


Fig. 7 - Forward Voltage Drop Characteristics

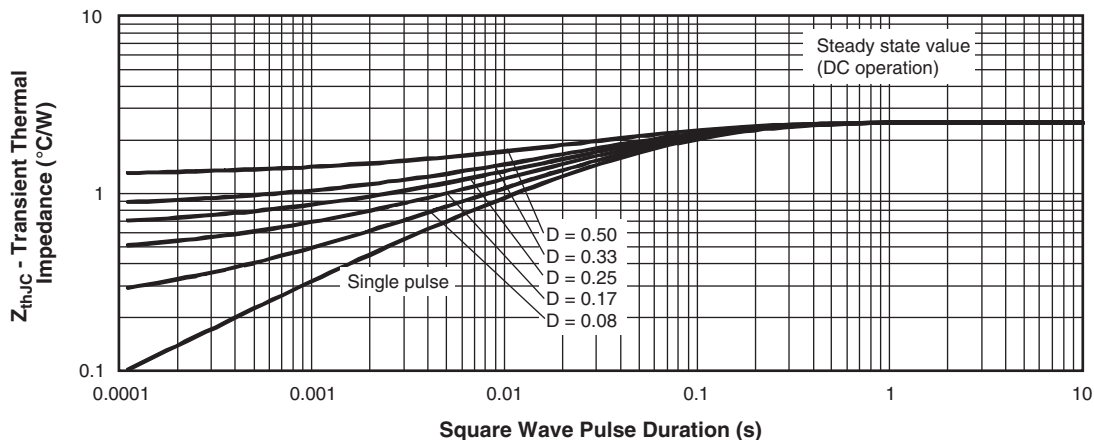


Fig. 8 - Thermal Impedance Z_{thJC} Characteristics



ORDERING INFORMATION TABLE

Device code	8	E	W	S	12	S	TR	PbF
	1	2	3	4	5	6	7	8

- | | | | |
|----------|---|---|---------------------------|
| 1 | - | Current rating (8 = 8 A) | |
| 2 | - | Circuit configuration: | |
| | | E = Single diode | |
| 3 | - | Package: | |
| | | W = D-PAK | |
| 4 | - | Type of silicon: | |
| | | S = Standard recovery rectifier | |
| 5 | - | Voltage ratings | 08 = 800 V
12 = 1200 V |
| 6 | - | S = Surface mountable | |
| 7 | - | • TR = Tape and reel
• TRR = Tape and reel (right oriented)
• TRL = Tape and reel (left oriented) | |
| 8 | - | PbF = Lead (Pb)-free | |

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95016
Part marking information	www.vishay.com/doc?95059
Packaging information	www.vishay.com/doc?95033

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension uncontrolled in L5
- Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.010") from the lead tip
- Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1 and c1 applied to base metal only
- Datum A and B to be determined at datum plane H
- Outline conforms to JEDEC outline TO-252AA



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